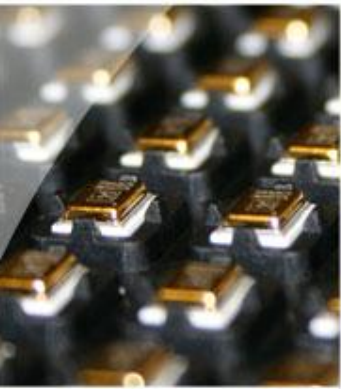


wi Spry

We make wireless work... better!



Integrated RF-CMOS MEMS Capacitors



Jeffrey L. Hilbert, President & Founder

June 22, 2010

➤ **Fabless RF Semiconductor Product Company**

- ✓ Enable Optimal Situational Performance for Wireless Devices through Dynamic Tuning
- ✓ Substantial Reduction in Size, Weight, Cost and Component Count for Frequency Agile Communications
 - Elimination of “Specialty” Passive Components – Integrating the Previously “Un-Integratable” Roadmap to Single Footprint Re-Configurable RF Front-End Solution

➤ **Uniquely Combine Scalability of CMOS Processing with WiSpry’s Patented Tunable Digital RF Capacitors**

- ✓ 80 Patents (38 Issued & Allowed; 42 Pending)

➤ **Strong Technology Leadership Position**

- ✓ Monolithic RF Integration; RF Performance and Range; Digital Control; Ultra-Low Power Consumption

➤ **In Design with Tier One Mobile Handset Provider**

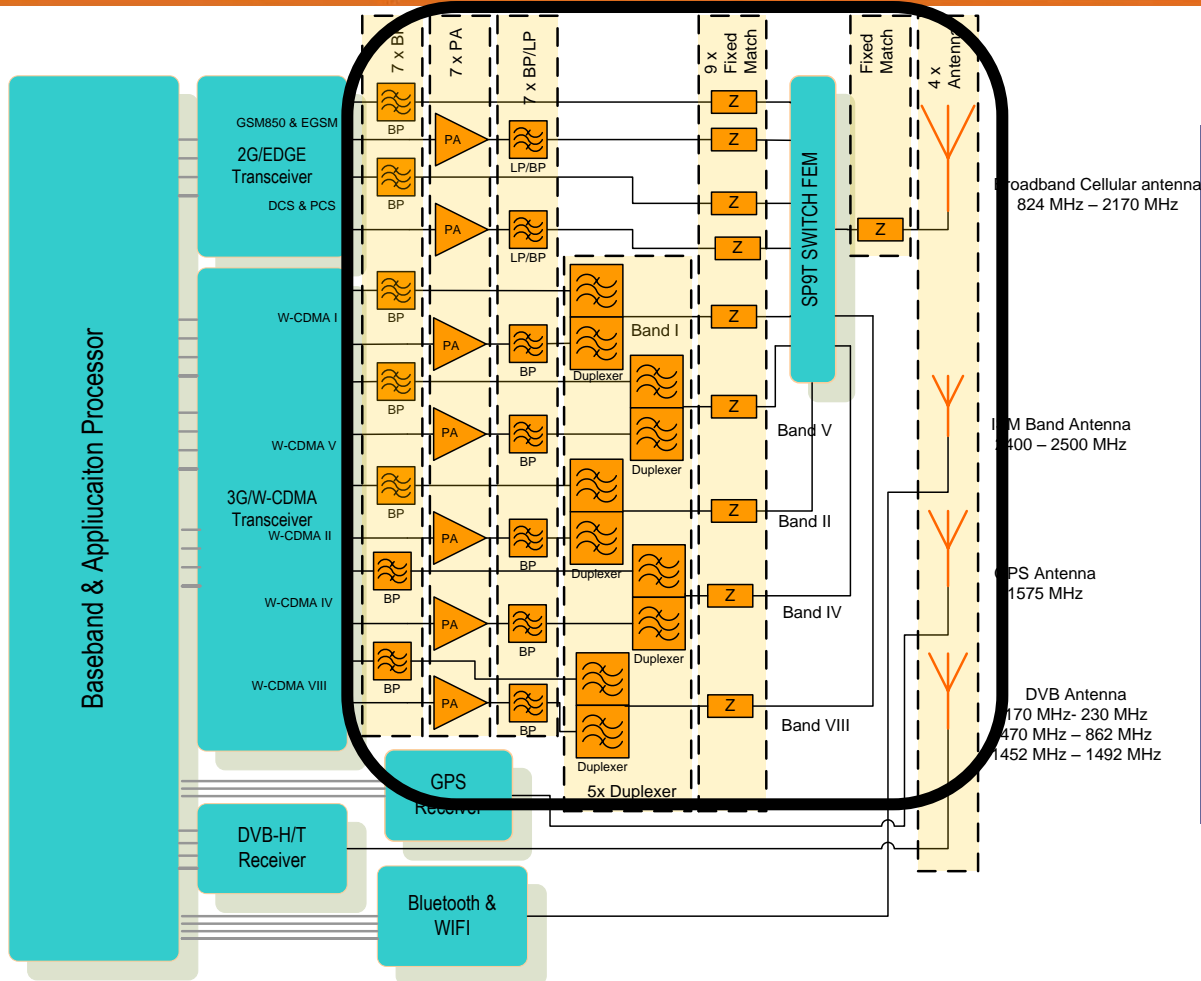
➤ **WiSpry**

- ✓ Established in October 2002; Core Team Engaged with Technology for >10 Years
- ✓ Irvine CA (Headquarters); RTP, NC; Seoul, Korea
- ✓ 37 Employees

3G / 4G Mobile Terminal Challenges



Integration of the RF Has Been Limited by Need for High Performance Specialty Solutions



- ⇒ One Chain of RF Components per Frequency or Mode
 - ⇒ More Cost, Space, & Power
- ⇒ Too Long of a Design Cycle for New Products
- ⇒ Too Much Customization Required for Every New Product
- ⇒ Compromised Performance

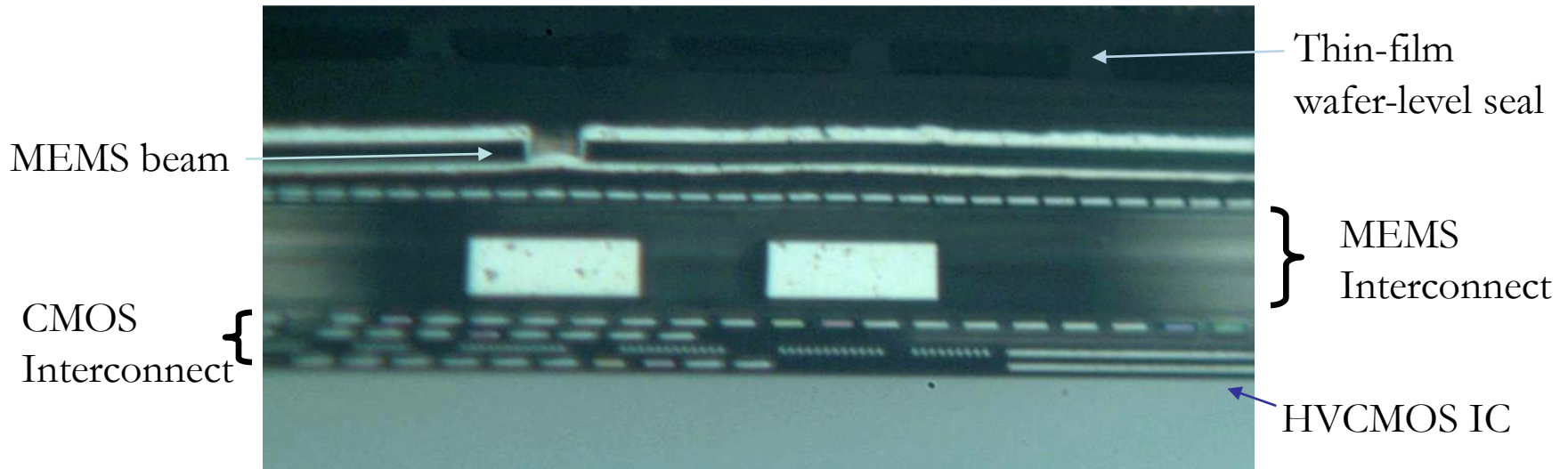
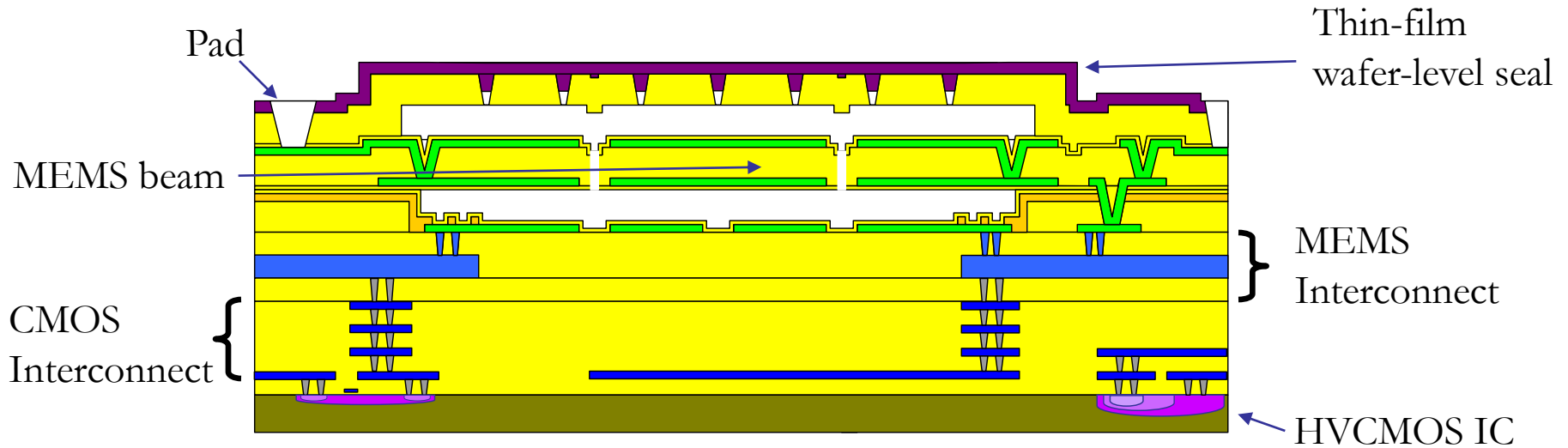
... And it Only Gets More Difficult with 4G / LTE

- Dynamically Reconfigure Properties / Performance of RF Functions Using Software

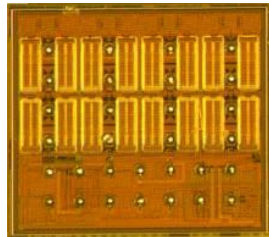
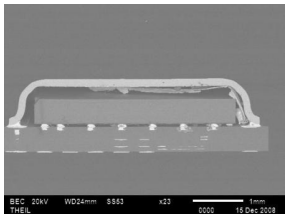
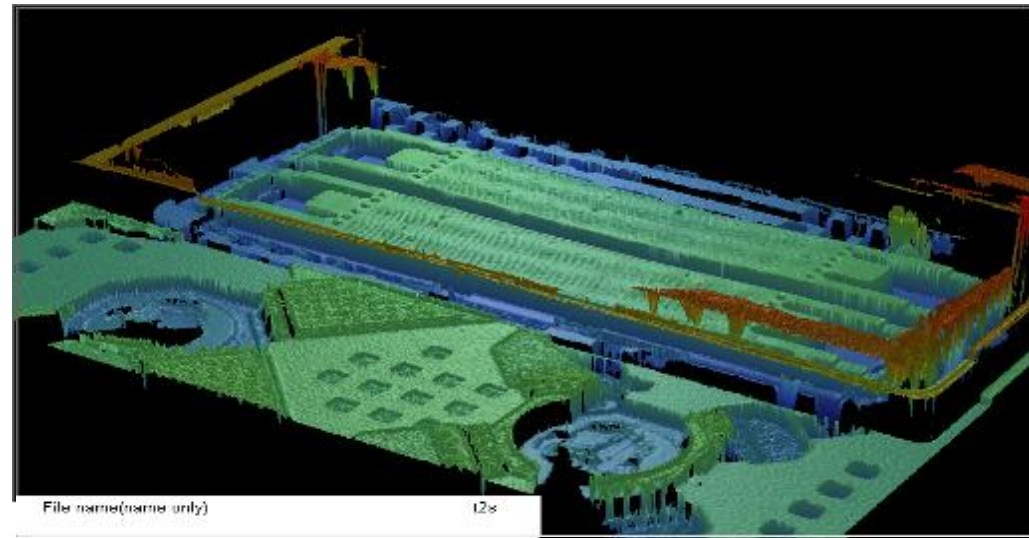
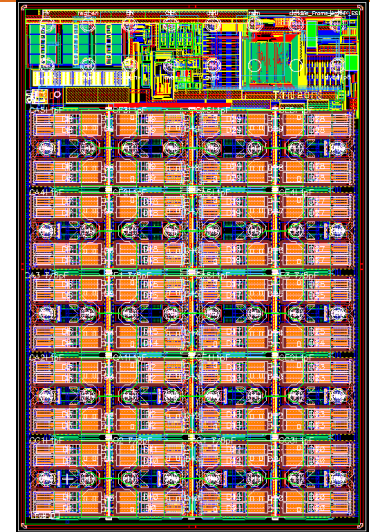
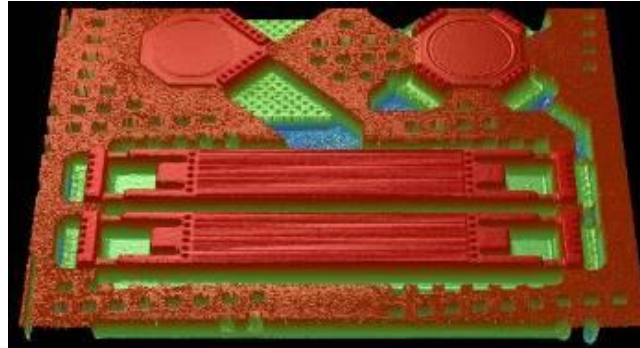
- Tunable, Re-Configurable, or Programmable RF Components

- Approaches Include
 - Switching
 - Modifying Material Properties
 - *Moving Micro-Scale Structures (RF-MEMS)*

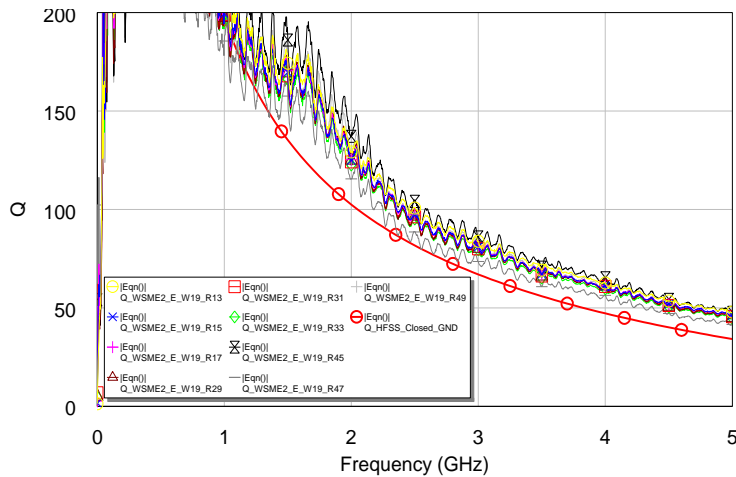
Silicon MEMS (On Top) Fabrication Process (0.18 μ m, 3/50V RF-CMOS Process; 8" Wafers)



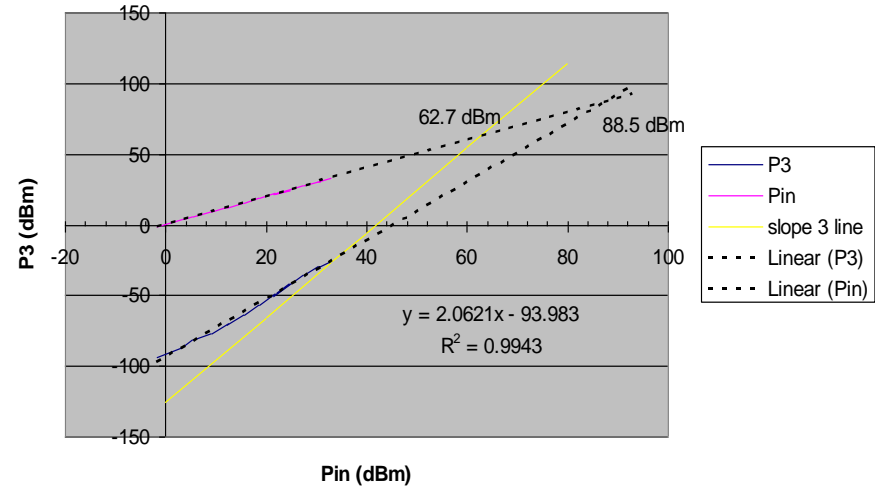
- Ultra Low Power with Superior Measured RF Performance
- High Device Density Provides Excellent Area Efficiency
- Precise Two-State Operation
- Scalable, Digital Architecture Supporting Many Different Tunable RF Applications and Combinations
- Integrated, Single Chip Solution Containing CMOS and MEMS
- Demonstrated Manufacturable and Reliable Structures



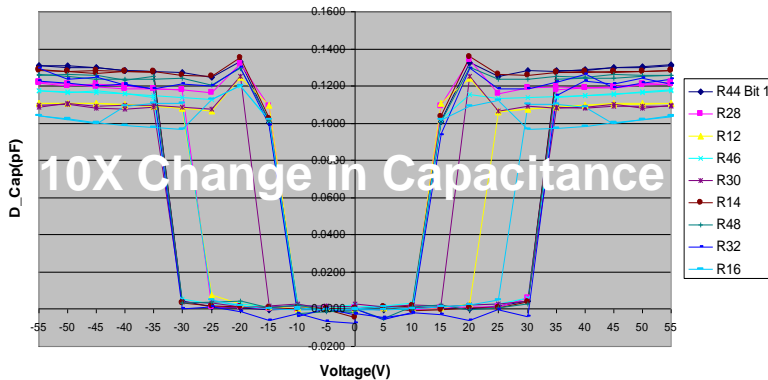
Q > 100 @ 2 GHz for 1pF Cell



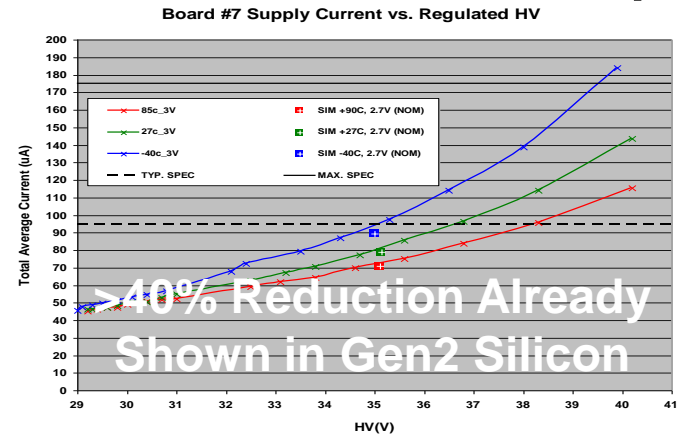
Ultra-Linear



High Capacitance Ratio

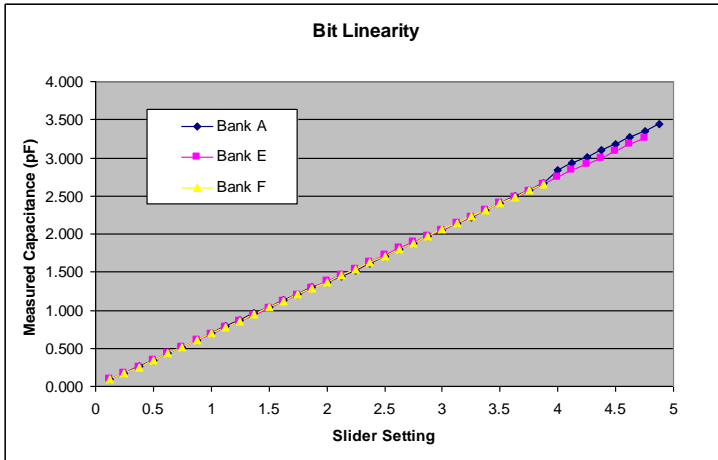


Ultra-Low Power Consumption

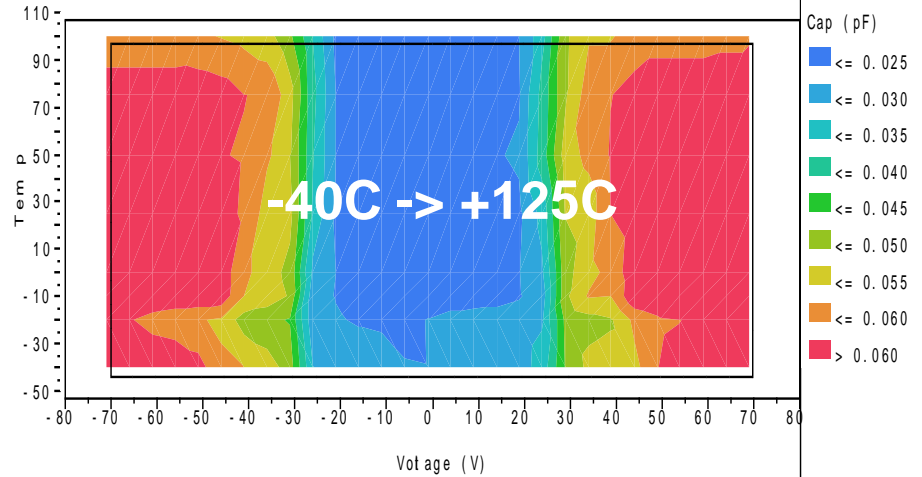


TDC Measured Data Highly Reliable and Robust

Excellent Bit Linearity

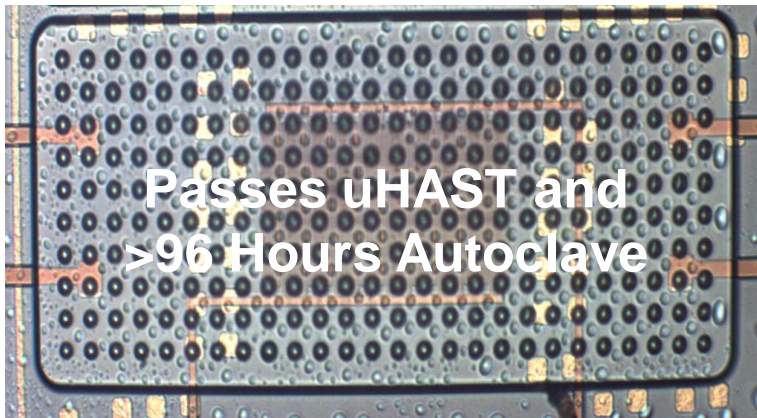


Temperature Stable



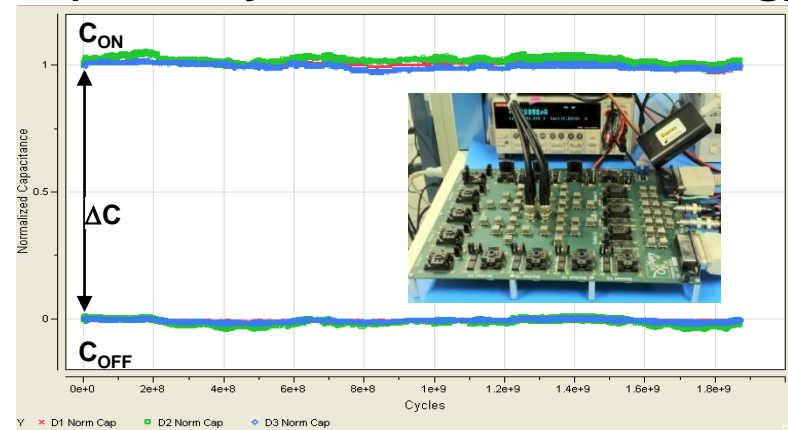
Hemeticity

(Wafer-level Encapsulation)



Long Life

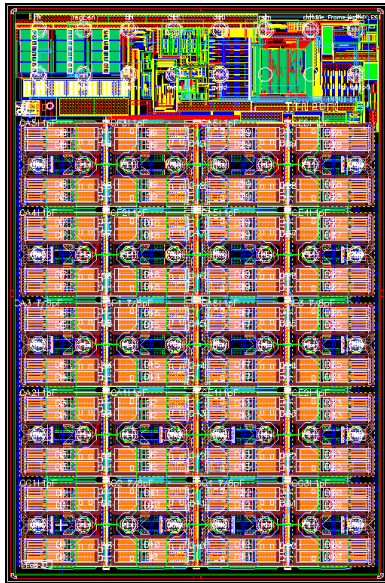
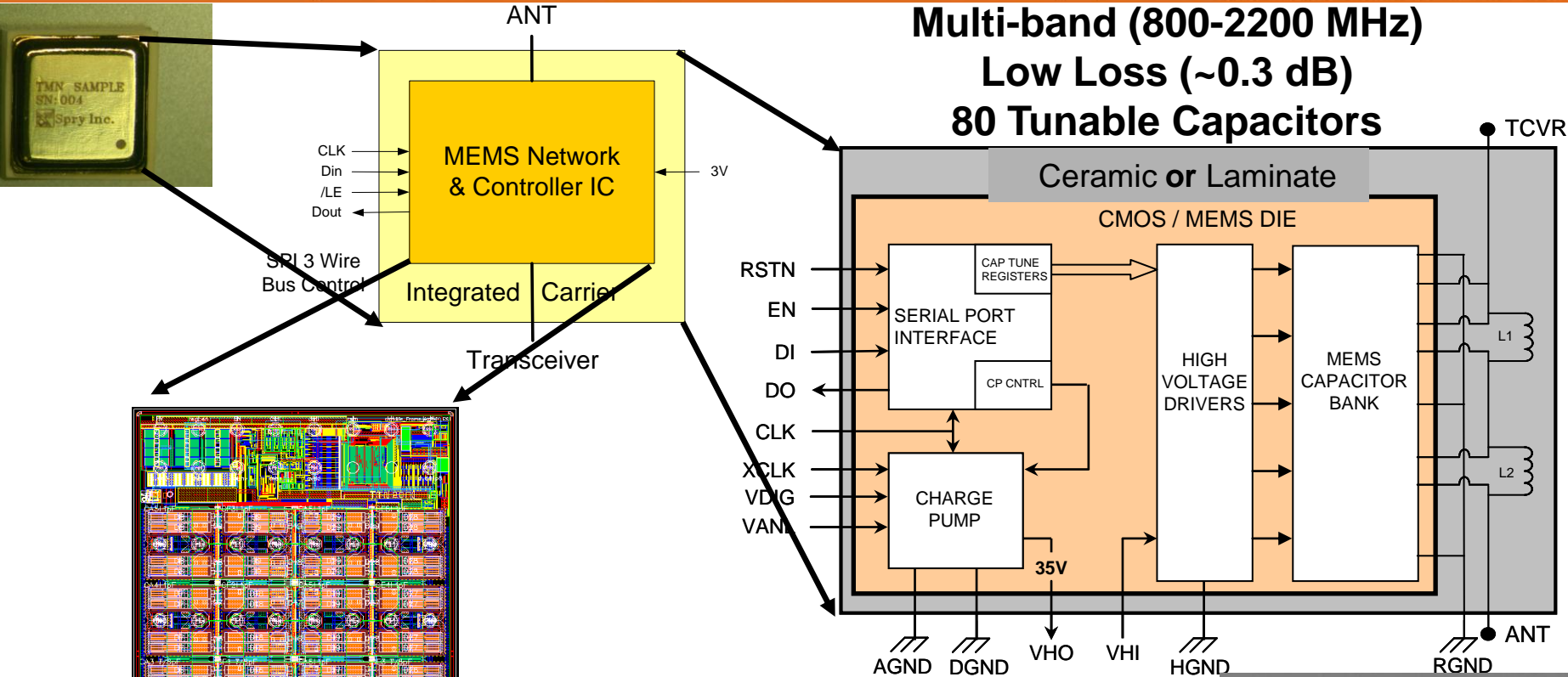
(> 1B Cycles in Parallel Testing)



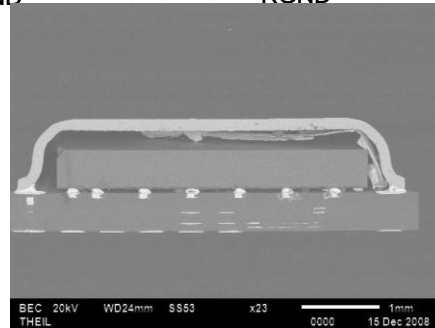
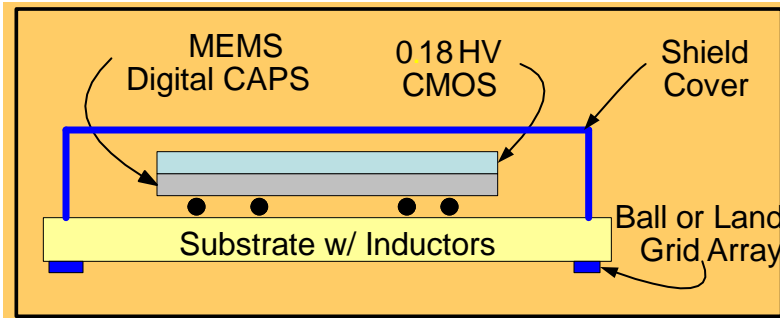
Example Application

Tunable Impedance Matching (TIM) Network

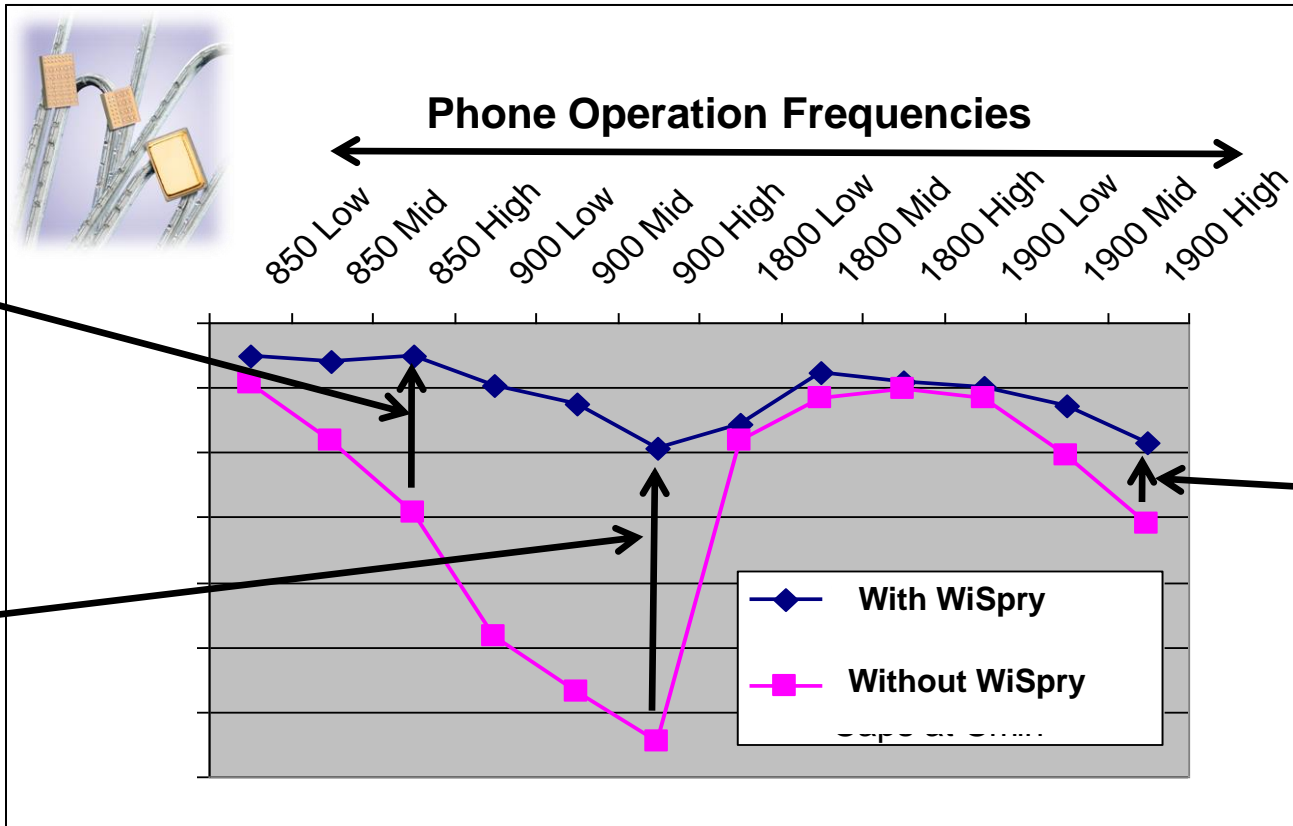
Multi-band (800-2200 MHz)
Low Loss (~0.3 dB)
80 Tunable Capacitors



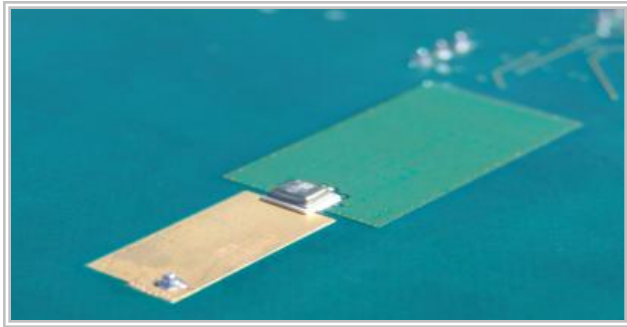
**Tunable Caps, Drivers, Serial Port
 Wafer Level Lid Seal**



Power Savings Measured WiSpry Product Performance



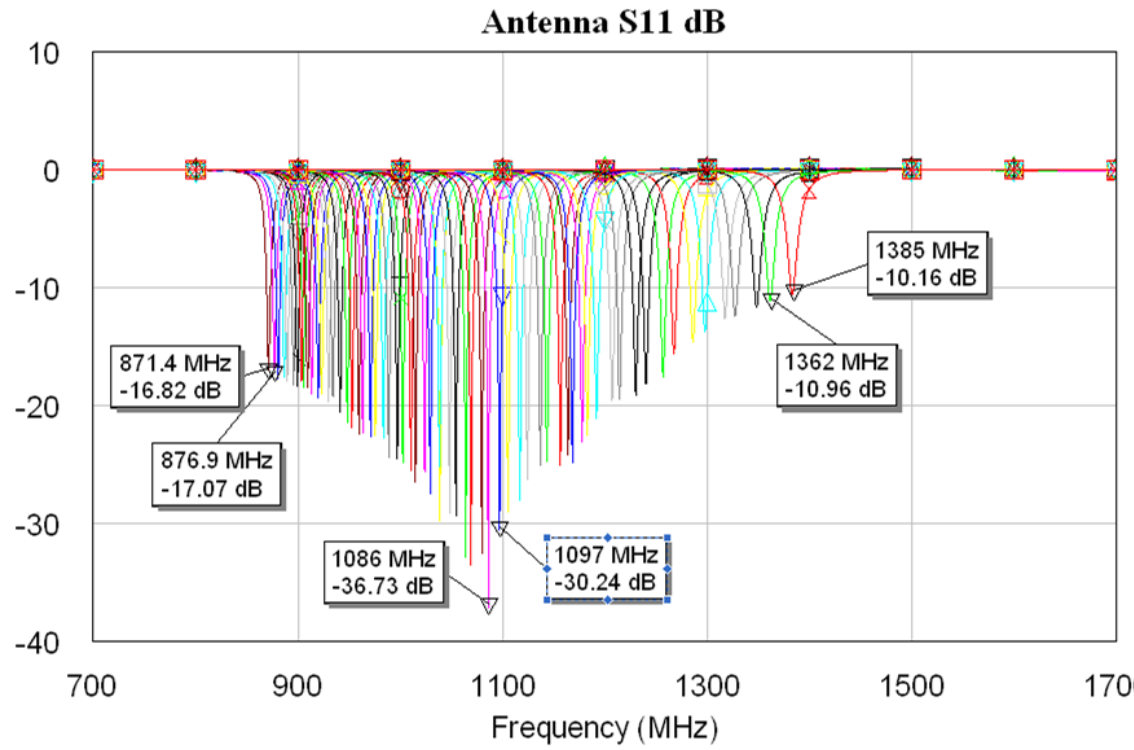
Engineering Sample Results on High Volume Production Phone



Demo TDCA tuning range – 3 to 11 pF

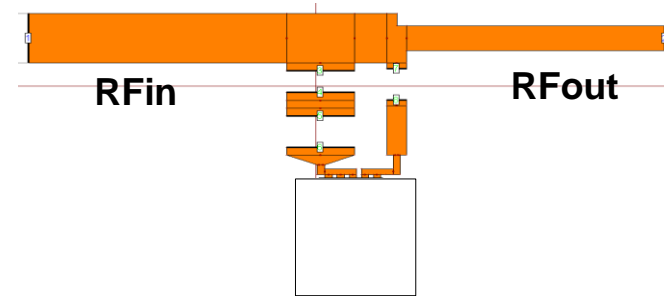
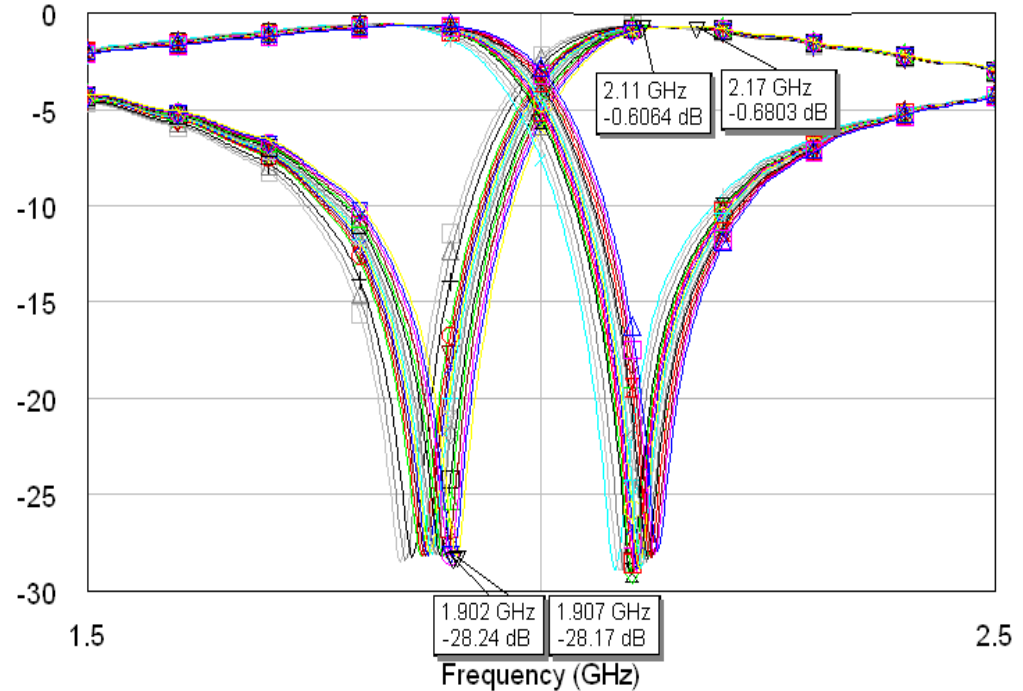
Low loss and highly linear tunable RF ICs enable antennas with:

- Tunability over at least one octave
- Sub-band operation
- Pre-select and spur suppression
- Impact on antenna volume (space) & efficiency by enabling:
 - Smaller volume & same efficiency, or
 - Same volume & higher efficiency
- Fairly omni-directional patterns
- Well-matched
- VSWR < 1.5:1 over passband

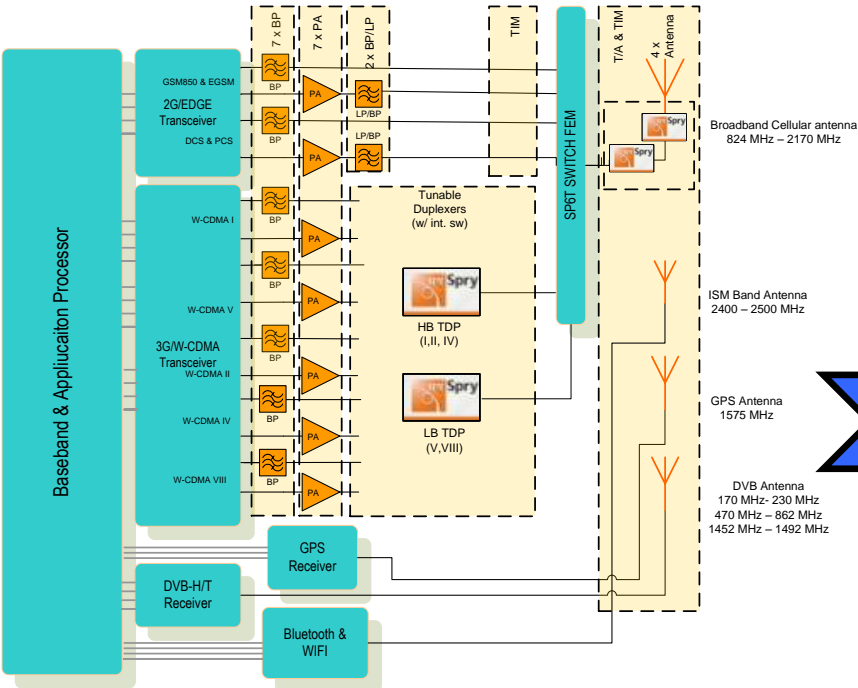




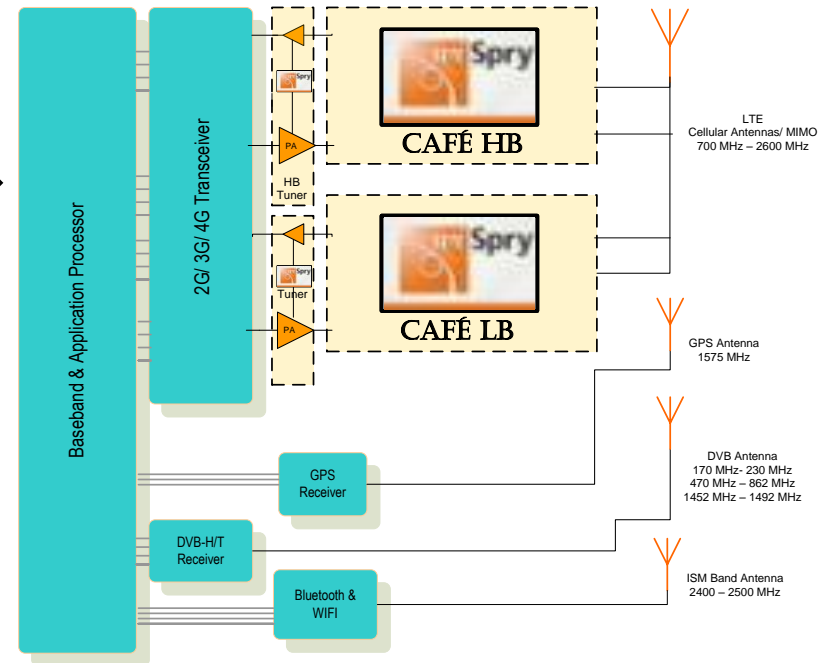
- Components:
 - SMD Air Core Inductor
 - Standard FR-4
 - Microstrip Line Based
 - 50 Ohms Input/Output
- Expected performance:
 - Insertion Loss ~0.7dB
 - Return Loss <-15dB
 - Rejection Level 23 dB
 - High-band Tunability
 - Variable Tx/Rx Spacing



Cooperative R&D Effort with Tier 1 Network Operator



Fully integrated Tunable RF Front-End



- Tunable Antenna Elements
- Tunable Low Noise Amplifier
- Tunable Antenna – Power Amplifier Matching
- Tunable Filters
- Tunable 3G Power Amplifier Tuners

NETWORK OPERATOR

Lower infrastructure costs
Increased network B/W & Improved OTA
Regional platform programmability
Decreased "churn"



SUBSCRIBER

Fewer dropped calls
Up to **30%** better battery life
More features – for less!
Talk everywhere @ anytime

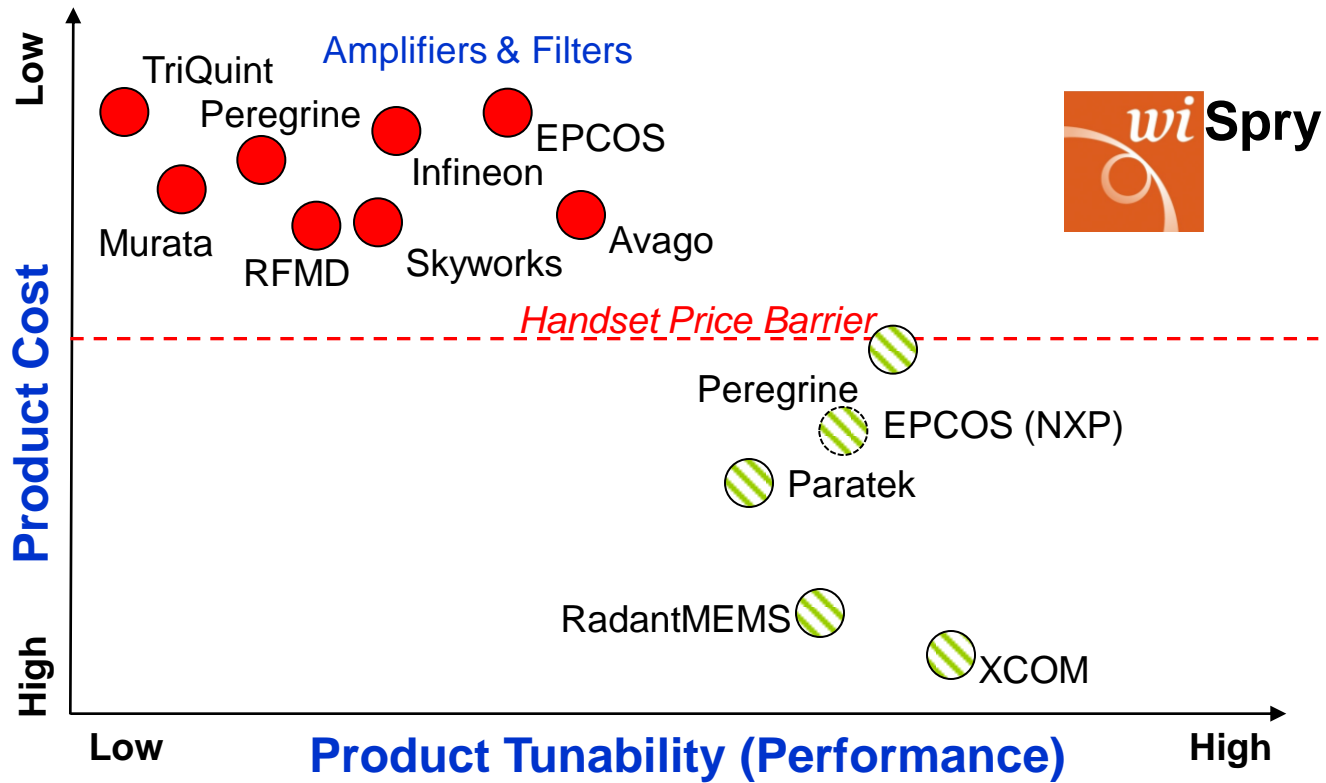


TERMINAL OEM

3dB + performance gain
Lower BOM
smaller & thinner form-factor
Increased battery life
Reduced SKUs
Faster time-to-market



Competitive Landscape



- 3G / 4G Mobile Terminals Require New Approaches to Integration of RF Front-End Functionality
- Tunable RF Components Based on Integrated RF-CMOS MEMS Balance Risk with Benefits
- Tunable Matching Networks, Antennas, and Filters Have Been Demonstrated Using a Digital Capacitor Array Architecture Implemented in 0.18um CMOS
- Research and Development of a First Generation Multiband Tunable Radio Front-End is in Progress

Questions?

Jeffrey L. Hilbert
President & Founder, WiSpry, Inc.
20 Fairbanks, Suite 198, Irvine, CA U.S.A. 92618
+1 949-458-9477 x200
jeff.hilbert@wispry.com